TinyLogic HST 2-Input NAND Gate

Description

The NC7ST00 is a single 2–Input high performance CMOS NAND Gate, with TTL–compatible inputs. Advanced Silicon Gate CMOS fabrication assures high speed and low power circuit operation. ESD protection diodes inherently guard both inputs and output with respect to the V_{CC} and GND rails. High gain circuitry offers high noise immunity and reduced sensitivity to input edge rate. The TTL–compatible inputs facilitate TTL to NMOS / CMOS interfacing. Device performance is similar to MM74HCT but with 1/2 the output current drive of HC / HCT.

Features

- Space Saving SC-74A and SC-88A 5-Lead Package
- Ultra Small MicroPak™ Leadless Package
- High Speed: t_{PD} < 7 ns Typ, V_{CC} = 5 V, C_L = 15 pF
- Low Quiescent Power: $I_{CC} < 1 \mu A$ Typ, $V_{CC} = 5.5 V$
- Balanced Output Drive: 2 mA I_{OL}, -2 mA I_{OH}
- TTL-compatible Inputs
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

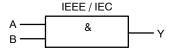


Figure 1. Logic Symbol



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SC-74A CASE 318BQ





SC-88A CASE 419A-02



E3, 8S00, T00 = Specific Device Code

KK = 2-Digit Lot Run Traceability Code XY = 2-Digit Date Code Format

Z = Assembly Plant Code
T = Die Run Code

= Year Coding Scheme
= Plant Code Identifier

= Eight-Week Datacoding Scheme

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 4 of this data sheet.

Pin Configurations

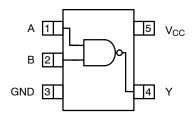


Figure 2. SC-88A and SC-74A (Top View)

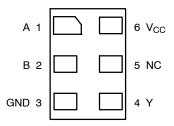


Figure 3. MicroPak (Top Through View)

PIN DESCRIPTIONS

Pin Names	Description
A, B	Inputs
Y	Output
NC	No Connect

FUNCTION TABLE $(Y = \overline{AB})$

Inp	Output	
Α	В	Υ
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

H = HIGH Logic Level L = LOW Logic Level

ABSOLUTE MAXIMUM RATINGS

Symbol	Paramete	Min	Max	Unit	
V _{CC}	Supply Voltage		-0.5	6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < -0.5 V	-	-20	mA
		$V_{IN} \ge V_{CC} + 0.5 V$	-	+20	
V _{IN}	DC Input Voltage		-0.5	V _{CC} + 0.5	V
I _{OK}	DC Output Diode Current	V _{OUT} < -0.5 V	-	-20	mA
		V _{OUT} > V _{CC} + 0.5 V	_	+20	
V _{OUT}	Output Voltage		-0.5	V _{CC} + 0.5	V
I _{OUT}	DC Output Source or Sink Current		-	±12.5	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current per Supp	oly Pin	=	±25	mA
T _{STG}	Storage Temperature		-65	+150	°C
TJ	Junction Temperature		=	+150	°C
TL	Lead Temperature (Soldering, 10 Seconds)		-	+260	°C
P_{D}	Power Dissipation in Still Air	SC-74A	-	225	mW
		SC-88A	_	190	
		MicroPak	-	327	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage		4.5	5.5	V
V _{IN}	Input Voltage		0	V _{CC}	V
V _{OUT}	Output Voltage		0	V _{CC}	V
T _A	Operating Temperature		-40	+85	°C
t _r , t _f	Input Rise and Fall Time	V _{CC} = 5.0 V	0	500	ns
θ_{JA}	Thermal Resistance	SC-74A	-	555	°C/W
		SC-88A	-	659	
		MicroPak	-	382	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTICAL CHARACTERISTICS

				-	Γ _A = +25°C	;	T _A = -40	to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Min	Тур	Max	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage	4.5 – 5.5		2.0	-	-	2.0	-	V
V _{IL}	LOW Level Input Voltage	4.5 – 5.5		-	-	0.8	_	8.0	V
V _{OH}	HIGH Level Output Voltage	4.5 4.5	$I_{OH} = -20 \ \mu A$ $I_{OH} = -2 \ mA$ $V_{IN} = V_{IL}$	4.4 4.18	4.5 4.35	-	4.4 4.13	-	٧
V _{OL}	LOW Level Output Voltage	4.5 4.5	$\begin{split} I_{OL} &= 20 \; \mu\text{A} \\ I_{OL} &= 2 \; \text{mA} \\ V_{IN} &= V_{IH} \end{split}$	-	0 0.10	0.1 0.26	-	0.1 0.33	٧
I _{IN}	Input Leakage Current	5.5	$0 \leq V_{IN} \leq 5.5 \ V$	-	-	±0.1	_	±1.0	μΑ
I _{CC}	Quiescent Supply Current	5.5	V _{IN} = V _{CC} or GND	-	_	1.0	_	10.0	μΑ
I _{CCT}	I _{CC} per Input	5.5	One Input V_{IN} = 0.5 V or 2.4 V, Other Input V_{CC} or GND	ı	-	2.0	-	2.9	mA

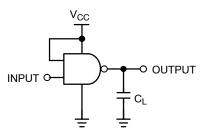
AC ELECTRICAL CHARACTERISTICS

					T _A = +25°($T_A = -40$	to +85°C			
Symbol Parameter	Parameter	nbol Parameter	Parameter	V _{CC} (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL} Propagation Delay (Figure 4, 6)	5.0	C _L = 15 pF	_	3.4	12	_	-	ns			
			_	6.3	17	_	-				
	4.5	C _L = 50 pF	-	6.0	16	-	20				
			-	11.5	27	-	31				
	5.5		-	4.1	14	-	18				
				-	11.2	26	-	30			
t _{TLH} , t _{THL}	Output Transition Time	5.0	C _L = 15 pF	-	4	10	-	-	ns		
	(Figure 4, 6)	4.5	C _L = 50 pF	_	11	25	-	31			
	5.5		-	10	21	-	26				
C _{IN}	Input Capacitance	Open		_	2	10	_	_	pF		
C _{PD}	Power Dissipation Capacitance (Figure 5)	5.0	(Note 2)	_	6	_	-	-	pF		

^{2.} C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current. Current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (See Figure 5). C_{PD} is related to I_{CCD} dynamic operating current by the expression: I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CCstatic}).

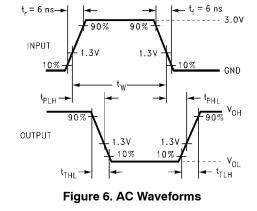
^{1.} Unused inputs must be held HIGH or LOW. They may not float.

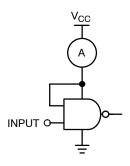
AC Loading and Waveforms



 C_L includes load and stray capacitance Input PRR = 1.0 MHz, $t_W = 500 \; \text{ns}$

Figure 4. AC Test Circuit





Input = AC Waveform;

PRR = Variable; Duty Cycle = 50%.

Figure 5. I_{CCD} Test Circuit

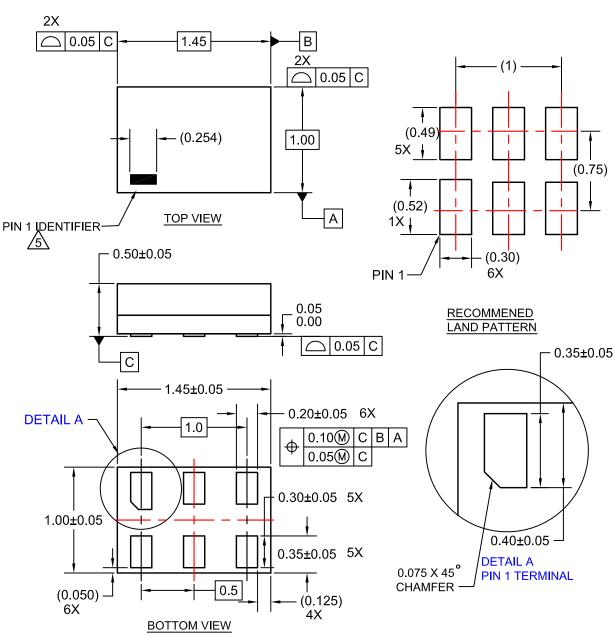
ORDERING INFORMATION

Device	Top Mark	Packages	Shipping [†]
NC7ST00M5X	8S00	SC-74A	3000 / Tape & Reel
NC7ST00P5X	T00	SC-88A	3000 / Tape & Reel
NC7ST00L6X	E3	SIP6, MicroPak	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

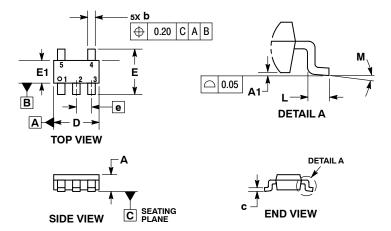
SIP6 1.45X1.0 CASE 127EB ISSUE O



- NOTES:
- 1. CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-2009
- 4. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY
 - OTHER LINE IN THE MARK CODE LAYOUT.

PACKAGE DIMENSIONS

SC-74A CASE 318BQ **ISSUE B**



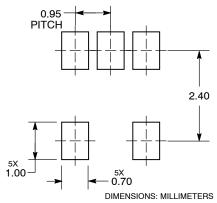
NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEPT 0.15 PER SIDE EXCEED 0.15 PER SIDE.

	MILLIMETERS					
DIM	MIN	MAX				
Α	0.90	1.10				
A1	0.01	0.10				
b	0.25	0.50				
С	0.10	0.26				
D	2.85	3.15				
E	2.50	3.00				
E1	1.35	1.65				
е	0.95 BSC					
L	0.20 0.60					
М	0 °	10°				

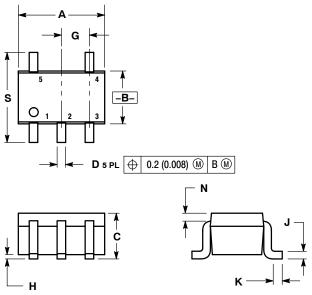
RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

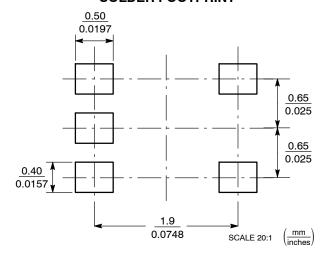
SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE L



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
С	0.031	0.043	0.80	1.10	
D	0.004	0.012	0.10	0.30	
G	0.026	BSC	0.65 BSC		
Н		0.004		0.10	
J	0.004	0.010	0.10	0.25	
K	0.004	0.012	0.10	0.30	
N	0.008 REF		0.20	REF	
S	0.079	0.087	2.00	2.20	

SOLDER FOOTPRINT



STYLE 1: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 5. COLLECTOR	STYLE 2:	STYLE 3:	STYLE 4:
	PIN 1. ANODE	PIN 1. ANODE 1	PIN 1. SOURCE 1
	2. EMITTER	2. N/C	2. DRAIN 1/2
	3. BASE	3. ANODE 2	3. SOURCE 1
	4. COLLECTOR	4. CATHODE 2	4. GATE 1
	5. CATHODE	5. CATHODE 1	5. GATE 2
STYLE 6:	STYLE 7:	STYLE 8: PIN 1. CATHODE 2. COLLECTOR 3. N/C 4. BASE 5. EMITTER	STYLE 9:
PIN 1. EMITTER 2	PIN 1. BASE		PIN 1. ANODE
2. BASE 2	2. EMITTER		2. CATHODE
3. EMITTER 1	3. BASE		3. ANODE
4. COLLECTOR	4. COLLECTOR		4. ANODE
5. COLLECTOR 2/BASE 1	5. COLLECTOR		5. ANODE

STYLE 5: PIN 1. CATHODE 2. COMMON ANODE 3. CATHODE 2 4. CATHODE 3 5. CATHODE 4

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